# **HEF4520B**

# **Dual binary counter**

Rev. 7 — 30 March 2016

**Product data sheet** 

### 1. General description

The HEF4520B is a dual 4-bit internally synchronous binary counter. The counter has an active HIGH clock input (nCP0) and an active LOW clock input (nCP1), buffered outputs from all four bit positions (nQ0 to nQ3) and an active HIGH overriding asynchronous master reset input (nMR).

The counter advances on either the LOW-to-HIGH transition of the nCP0 input if  $\overline{nCP1}$  is HIGH or the HIGH-to-LOW transition of the nCP1 input if nCP0 is LOW. Either nCP0 or nCP1 may be used as the clock input to the counter while the other clock input may be used as a clock enable input. Schmitt trigger action makes the clock input highly tolerant of slower clock rise and fall times. A HIGH on nMR resets the counter (nQ0 to nQ3 = LOW) independent of nCP0 and nCP1.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

### 2. Features and benefits

- Tolerant of slow clock rise and fall times
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from –40 °C to +85 °C
- Complies with JEDEC standard JESD 13-B

# 3. Ordering information

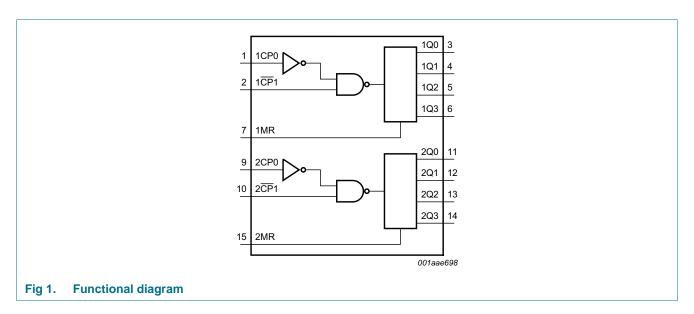
#### Table 1. Ordering information

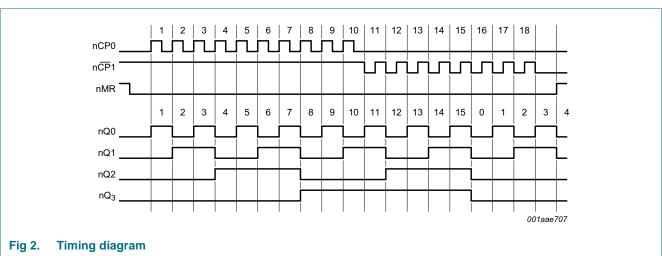
All types operate from −40 °C to +85 °C.

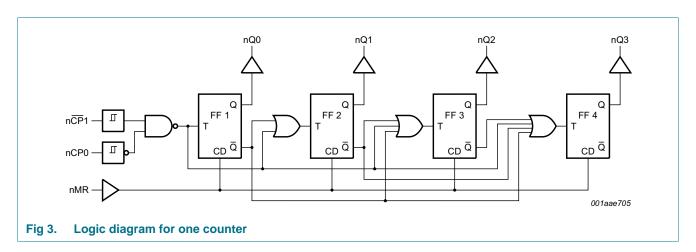
Type number Package								
	Name	Description	Version					
HEF4520BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1					



# 4. Functional diagram

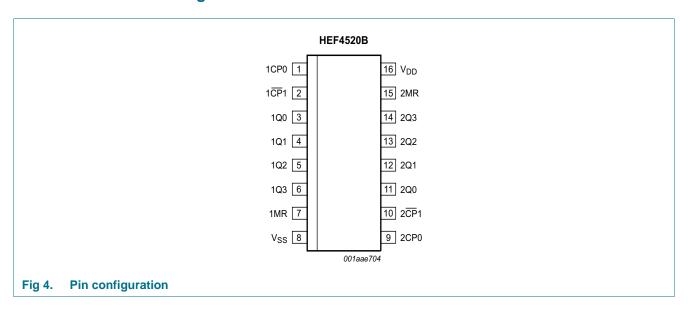






# 5. Pinning information

### 5.1 Pinning



## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1CP0, 2CP0	1, 9	clock input (LOW-to-HIGH triggered)
1CP1, 2CP1	2, 10	clock input (HIGH-to-LOW triggered)
1Q0 to 1Q3	3, 4, 5, 6	output
1MR, 2MR	7, 15	master reset input
V <sub>SS</sub>	8	ground supply voltage
2Q0 to 2Q3	11, 12, 13, 14	output
$V_{DD}$	16	supply voltage

# 6. Functional description

Table 3. Function table[1]

nCP0	nCP1	nMR	Mode
<b>↑</b>	Н	L	counter advances
L	<b>↓</b>	L	counter advances
<b>\</b>	X	L	no change
X	$\uparrow$	L	no change
$\uparrow$	L	L	no change
Н	<b>↓</b>	L	no change
X	X	Н	nQ0 to nQ3 = LOW

<sup>[1]</sup>  $H = HIGH \text{ voltage level}; L = LOW \text{ voltage level}; X = don't care; \uparrow = positive-going transition; } \downarrow = negative-going transition.$ 

HEF4520B

# 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DD}$	supply voltage			-0.5	+18	V
I <sub>IK</sub>	input clamping current	$V_{I} < -0.5 \text{ V or } V_{I} > V_{DD} + 0.5 \text{ V}$		-	±10	mA
VI	input voltage			-0.5	V <sub>DD</sub> + 0.5	V
I <sub>OK</sub>	output clamping current	$V_{O} < -0.5 \text{ V or } V_{O} > V_{DD} + 0.5 \text{ V}$		-	±10	mA
I <sub>I/O</sub>	input/output current			-	±10	mA
I <sub>DD</sub>	supply current			-	50	mA
T <sub>stg</sub>	storage temperature	per output		-65	+150	°C
T <sub>amb</sub>	ambient temperature			-40	+85	°C
P <sub>tot</sub>	total power dissipation	SO16 package	[1]	-	500	mW
Р	power dissipation			-	100	mW

<sup>[1]</sup> For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

# 8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{DD}$	supply voltage		3	-	15	V
V <sub>I</sub>	input voltage		0	-	$V_{DD}$	V
T <sub>amb</sub>	ambient temperature	in free air	-40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V <sub>DD</sub> = 5 V	-	-	3.75	μs/V
		V <sub>DD</sub> = 10 V	-	-	0.5	μs/V
		V <sub>DD</sub> = 15 V	-	-	0.08	μs/V

# 9. Static characteristics

Table 6. Static characteristics

 $V_{SS} = 0$  V;  $V_I = V_{SS}$  or  $V_{DD}$  unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	T <sub>amb</sub> =	–40 °C	T <sub>amb</sub> =	25 °C	T <sub>amb</sub> = 85 °C		Unit
				Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_{O}  < 1 \mu A$	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_{O}  < 1 \mu A$	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
V <sub>OH</sub>	HIGH-level output voltage		5 V	4.95	-	4.95	-	4.95	-	V
		$V_I = V_{SS}$ or $V_{DD}$	10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
V <sub>OL</sub> I	LOW-level output voltage	$ I_O  < 1 \mu A;$ $V_I = V_{SS} \text{ or } V_{DD}$	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
I <sub>OH</sub>	HIGH-level output current	V <sub>O</sub> = 2.5 V	5 V	-	-1.7	-	-1.4	-	-1.1	mA
		V <sub>O</sub> = 4.6 V	5 V	-	-0.52	-	-0.44	-	-0.36	mA
		V <sub>O</sub> = 9.5 V	10 V	-	-1.3	-	-1.1	-	-0.9	mA
		V <sub>O</sub> = 13.5 V	15 V	-	-3.6	-	-3.0	-	-2.4	mA
I <sub>OL</sub>	LOW-level output current	V <sub>O</sub> = 0.4 V	5 V	0.52	-	0.44	-	0.36	-	mA
		V <sub>O</sub> = 0.5 V	10 V	1.3	-	1.1	-	0.9	-	mA
		V <sub>O</sub> = 1.5 V	15 V	3.6	-	3.0	-	2.4	-	mA
I <sub>I</sub>	input leakage current	V <sub>DD</sub> = 15 V	15 V	-	±0.3	-	±0.3	-	±1.0	μΑ
I <sub>DD</sub>	supply current	I <sub>O</sub> = 0 A;	5 V	-	20	-	20	-	150	μΑ
		$V_I = V_{SS}$ or $V_{DD}$	10 V	-	40	-	40	-	300	μΑ
			15 V	-	80	-	80	-	600	μΑ
Cı	input capacitance		-	-	-	-	7.5	-	-	pF

# 10. Dynamic characteristics

Table 7. Dynamic characteristics

 $V_{SS} = 0 \text{ V}$ ;  $T_{amb} = 25 \text{ °C}$ ; for test circuit see Figure 6; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula	Min	Тур	Max	Unit
t <sub>PHL</sub>	HIGH to LOW	nCP0, n $\overline{CP1} \rightarrow nQn$ ;	5 V [1]	83 ns + (0.55 ns/pF)C <sub>L</sub>	-	110	220	ns
	propagation delay	see <u>Figure 5</u>	10 V	39 ns + (0.23 ns/pF)C <sub>L</sub>	-	50	100	ns
			15 V	32 ns + (0.16 ns/pF)C <sub>L</sub>	-	40	80	ns
		$nMR \rightarrow nQn;$	5 V	48 ns + (0.55 ns/pF)C <sub>L</sub>	-	75	150	ns
	see Figure 5	10 V	24 ns + (0.23 ns/pF)C <sub>L</sub>	-	35	70	ns	
			15 V	17 ns + (0.16 ns/pF)C <sub>L</sub>	-	25	50	ns

 Table 7.
 Dynamic characteristics ...continued

 $V_{SS} = 0 \text{ V; } T_{amb} = 25 \text{ °C; for test circuit see } \frac{\text{Figure 6}}{\text{circuit see }}; \text{ unless otherwise specified.}$ 

Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula	Min	Тур	Max	Unit
t <sub>PLH</sub>	LOW to HIGH	nCP0, n $\overline{CP1} \rightarrow nQn$ ;	5 V [1]	83 ns + (0.55 ns/pF)C <sub>L</sub>	-	110	220	ns
	propagation delay	see Figure 5	10 V	39 ns + (0.23 ns/pF)C <sub>L</sub>	-	50	100	ns
			15 V	32 ns + (0.16 ns/pF)C <sub>L</sub>	-	40	80	ns
t <sub>t</sub>	transition time	nQn; see Figure 5	5 V [1]	10 ns + (1.00 ns/pF)C <sub>L</sub>	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C <sub>L</sub>	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C <sub>L</sub>	-	20	40	ns
t <sub>W</sub>	pulse width	nCP0 input LOW;	5 V		60	30	-	ns
		minimum width; see Figure 5	10 V		30	15	-	ns
		see <u>Figure 5</u>	15 V		20	10	-	ns
		nCP1 input HIGH;	5 V		60	30	-	ns
		minimum width; see Figure 5	10 V		30	15	-	ns
		see <u>Figure 5</u>	15 V		20	10	-	ns
		nMR input HIGH;	5 V		30	15	-	ns
		minimum width; see Figure 5	10 V		20	10	-	ns
		see <u>Figure 5</u>	15 V		16	8	-	ns
t <sub>su</sub>	set-up time	$nCP0 \rightarrow n\overline{CP}1;$	5 V		50	25	-	ns
		see Figure 5	10 V		30	15	-	ns
			15 V		20	10	-	ns
		$n\overline{CP}1 \rightarrow nCP0;$	5 V		50	25	-	ns
		see Figure 5	10 V		30	15	-	ns
			15 V		20	10	-	ns
t <sub>rec</sub>	recovery time	see Figure 5	5 V		50	25	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
f <sub>max</sub>	maximum	nCP0, nCP1;	5 V		8	16	-	MHz
	frequency	see Figure 5	10 V		15	30	-	MHz
			15 V		20	40	-	MHz

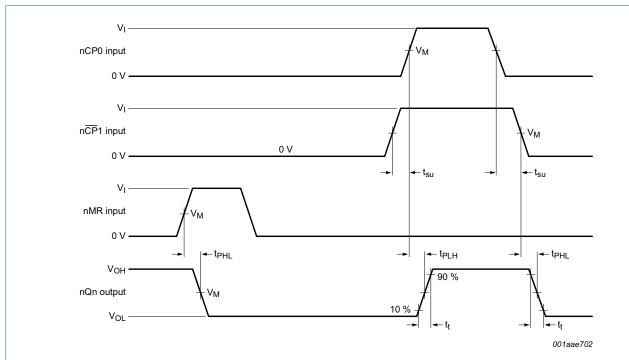
<sup>[1]</sup> The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown ( $C_L$  in pF).

Table 8. Dynamic power dissipation P<sub>D</sub>

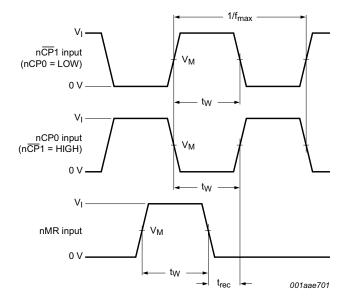
 $P_D$  can be calculated from the formulas shown.  $V_{SS} = 0 \ V$ ;  $t_r = t_f \le 20 \ ns$ ;  $T_{amb} = 25 \ ^{\circ}C$ .

Symbol	Parameter	$V_{DD}$	Typical formula for P <sub>D</sub> (μW)	Where:
$P_D$	dynamic power	5 V	$P_D = 850 \times f_i + \Sigma (f_o \times C_L) \times V_{DD}^2$	$f_i$ = input frequency in MHz,
	dissipation	10 V	$P_D = 3800 \times f_i + \Sigma (f_0 \times C_L) \times V_{DD}^2$	fo = output frequency in MHz,
		15 V	$P_D = 10200 \times f_i + \Sigma (f_0 \times C_L) \times V_{DD}^2$	$C_L$ = output load capacitance in pF,
				$V_{DD}$ = supply voltage in V,
				$\Sigma(f_0 \times C_L)$ = sum of the outputs.

### 11. Waveforms

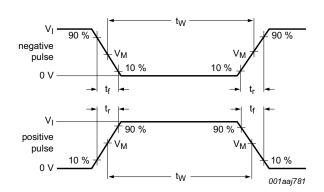


a. nCP0 and nCP1 set-up times, propagation delays and output transition times

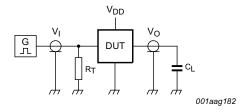


b. nMR recovery time, minimum nCP0, nCP1, and nMR pulse widths and maximum frequency
 Measurement points are given in Table 9.
 The logic levels V<sub>OH</sub> and V<sub>OL</sub> are typical output voltage levels that occur with the output load.

Fig 5. Waveforms showing measurements for switching times



#### a. Input waveforms



#### b. Test circuit

Test data is given in Table 9.

Definitions for test circuit:

DUT = Device Under Test;

C<sub>L</sub> = Load capacitance including jig and probe capacitance;

 $R_T$  = Termination resistance should be equal to output impedance  $Z_0$  of the pulse generator.

Fig 6. Test circuit for measuring switching times

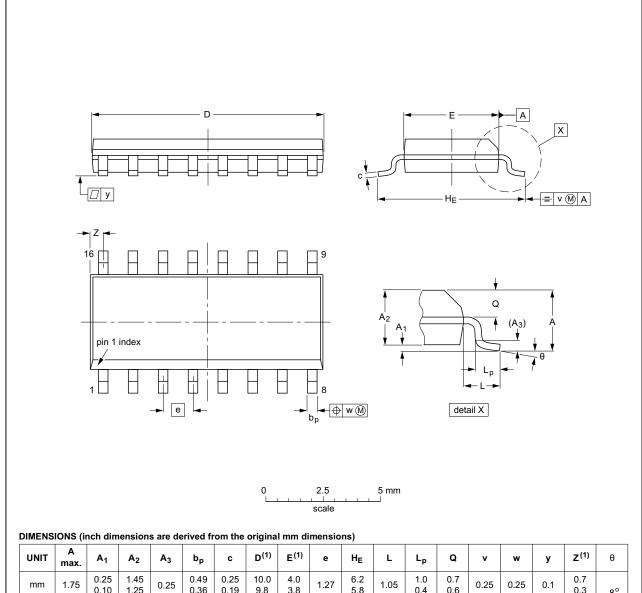
Table 9. Measurement points and test data

Supply voltage	Input	Load		
$V_{DD}$	VI	V <sub>M</sub>	t <sub>r</sub> , t <sub>f</sub>	C <sub>L</sub>
5 V to 15 V	$V_{DD}$	0.5V <sub>I</sub>	≤ 20 ns	50 pF

# 12. Package outline

### SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	<b>A</b> <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	٧	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT109-1	076E07	MS-012				<del>99-12-27</del> 03-02-19

Fig 7. Package outline SOT109-1 (SO16)

HEF4520B

# 13. Revision history

### Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes		
HEF4520B v.7	20160330	Product data sheet	-	HEF4520B v.6		
Modifications:	Type number	Type number HEF4520BP (SOT38-4) removed.				
HEF4520B v.6	20111118	Product data sheet	-	HEF4520B v.5		
Modifications:	Section App	Section Applications removed				
	<u>Table 6</u> : I <sub>OH</sub> minimum values changed to maximum					
HEF4520B v.5	20091210	Product data sheet	-	HEF4520B v.4		
HEF4520B v.4	20090828	Product data sheet	-	HEF4520B_CNV v.3		
HEF4520B_CNV v.3	19950101	Product specification	-	HEF4520B_CNV v.2		
HEF4520B_CNV v.2	19950101	Product specification	-	-		

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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